

ABSTRACT OF THE DISCLOSURE

In a heat dissipating device, a heat-conducting unit is disposed in a housing and has a first heat-conducting member mounted on a circuit board inside the housing and contacting and in thermal communication with an electronic component mounted on the circuit board, and a second heat-conducting member that has a first end portion connected to the first heat-conducting member, and a second end portion opposite to the first end portion and extending outwardly of the housing through a through hole in the housing. A heat-dissipating fin module is mounted externally of the housing, and has a base plate connected to and in thermal communication with the second end portion of the second heat-conducting member, and a plurality of fin posts mounted fixedly and spacedly on and in thermal communication with the base plate.